Features

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

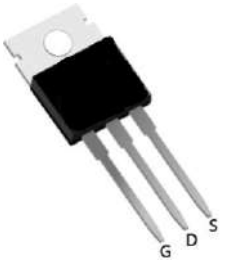
Product Summary

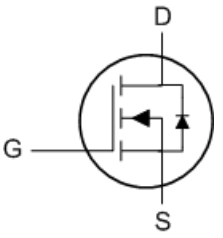
RoHs

V_{DS}	60	V
$R_{DS(on),MAX}$@ V_{GS}=10 V	4.8	mΩ
I_D	170	A

Application

- DC/DC Converters
- Power Management in Inverter System





TO-220

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@T_C=25℃	Continuous Drain Current, V_{GS} @ 10V[1,6]	170	A
I_D@T_C=100℃	Continuous Drain Current, V_{GS} @ 10V[1,6]	107	A
I_D@T_A=25℃	Continuous Drain Current, V_{GS} @ 10V[1]	150	A
I_D@T_A=70℃	Continuous Drain Current, V_{GS} @ 10V[1]	120	A
I_{DM}	Pulsed Drain Current[2]	340	A
EAS	Single Pulse Avalanche Energy[3]	245	mJ
I_{AS}	Avalanche Current	70	A
P_D@T_C=25℃	Total Power Dissipation[4]	260	W
P_D@T_A=25℃	Total Power Dissipation[4]	2.02	W
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient [1]	---	62	℃/W
$R_{\theta JC}$	Thermal Resistance Junction-Case[1]	---	0.48	℃/W

Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	60	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BV_{DSS} Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	0.058	---	V/℃
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V , I_D=30A	---	---	4.8	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	2.5	---	4.5	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-7.8	---	mV/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=60V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=60V , V_{GS}=0V , T_J=55℃	---	---	5	
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
gfs	Forward Transconductance	V_{DS}=5V , I_D=30A	---	50	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	1.4	---	Ω
Q_g	Total Gate Charge (10V)	V_{DS}=48V , V_{GS}=10V , I_D=15A	---	83.7	---	nC
Q_{gs}	Gate-Source Charge		---	28.6	---	
Q_{gd}	Gate-Drain Charge		---	29.3	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=30V , V_{GS}=10V , R_G=3.3Ω, I_D=48A	---	38.1	---	ns
T_r	Rise Time		---	73.3	---	
$T_{d(off)}$	Turn-Off Delay Time		---	51.6	---	
T_f	Fall Time		---	26.1	---	
C_{iss}	Input Capacitance	V_{DS}=15V , V_{GS}=0V , f=1MHz	---	5580	---	pF
C_{oss}	Output Capacitance		---	571	---	
C_{rss}	Reverse Transfer Capacitance		---	278	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current[1,5]	V_G=V_D=0V , Force Current	---	---	170	A
I_{SM}	Pulsed Source Current[2,5]		---	---	340	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1.2	V
t_{rr}	Reverse Recovery Time	I_F=30A , dI/dt=100A/μs , T_J=25℃	---	27	---	nS
Q_{rr}	Reverse Recovery Charge		---	28	---	nC

Note :
1.The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper.
2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%
3.The EAS data shows Max. rating . The test condition is V_{DD}=50V,V_{GS}=10V,L=0.1mH,I_{AS}=70A
4.The power dissipation is limited by 150℃ junction temperature
5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.
6.Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 170A.

Typical Characteristics

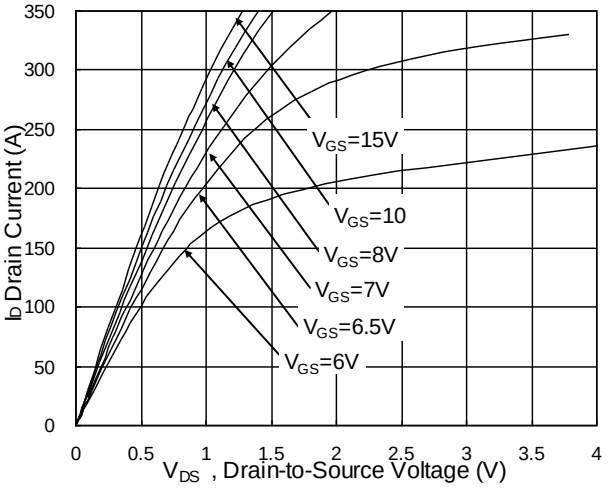


Fig.1 Typical Output Characteristics

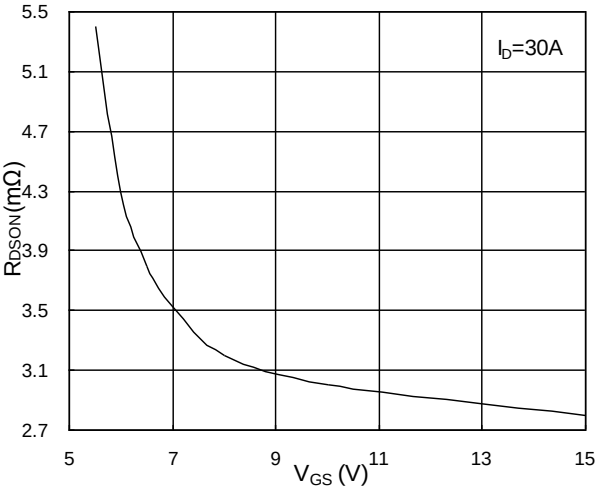


Fig.2 On-Resistance v.s Gate-Source

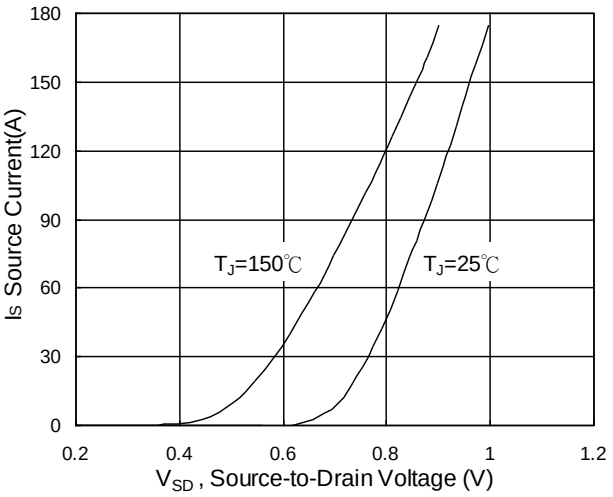


Fig.3 Forward Characteristics of Reverse

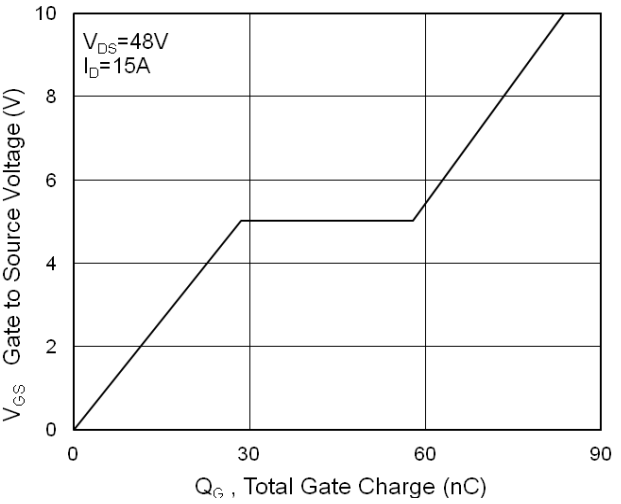


Fig.4 Gate-Charge Characteristics

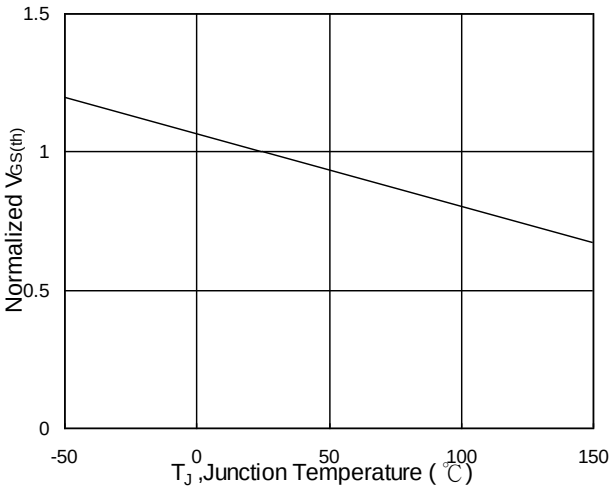


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

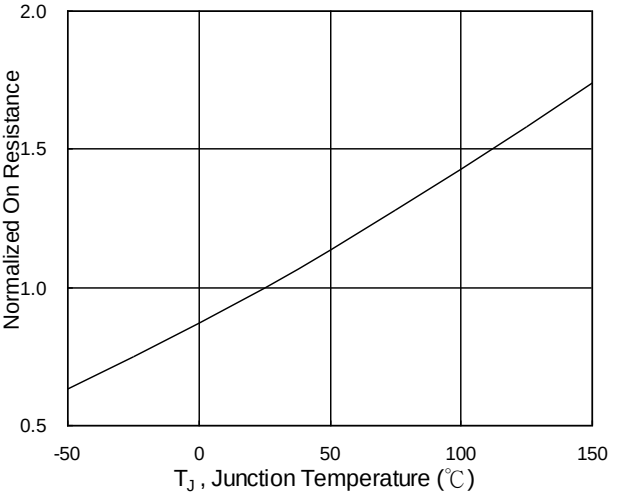


Fig.6 Normalized R_{DSON} v.s T_J

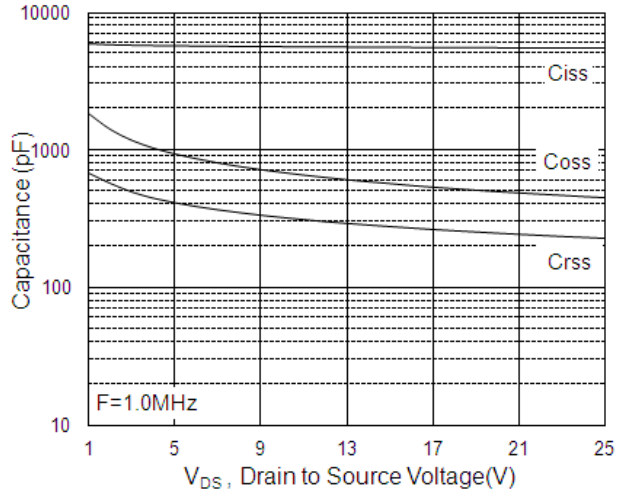


Fig.7 Capacitance

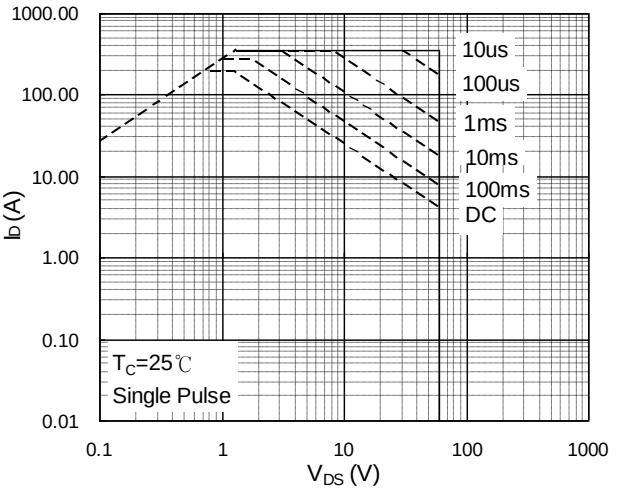


Fig.8 Safe Operating Area

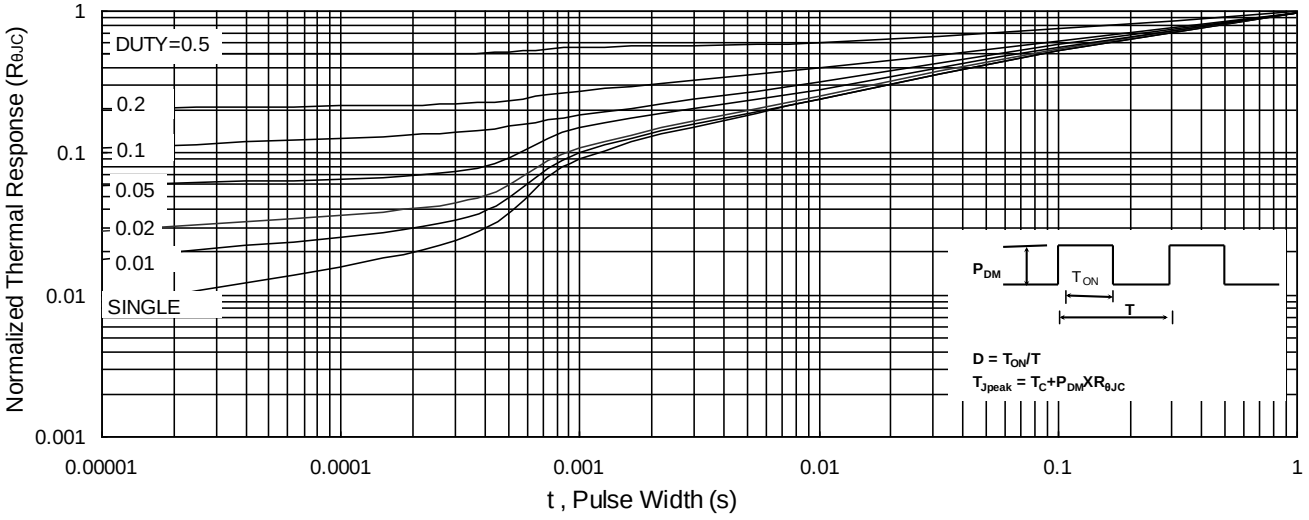


Fig.9 Normalized Maximum Transient Thermal Impedance

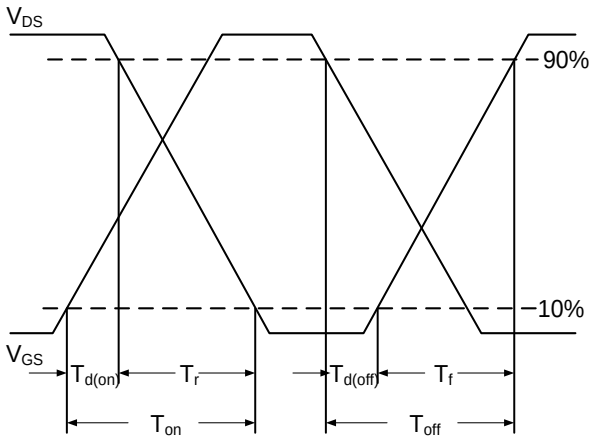


Fig.10 Switching Time Waveform

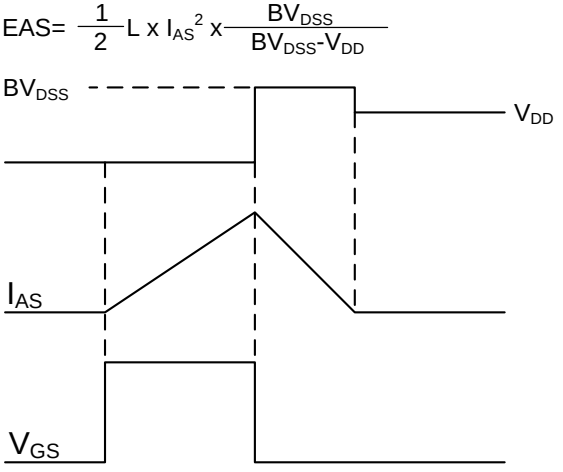
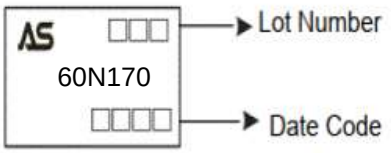


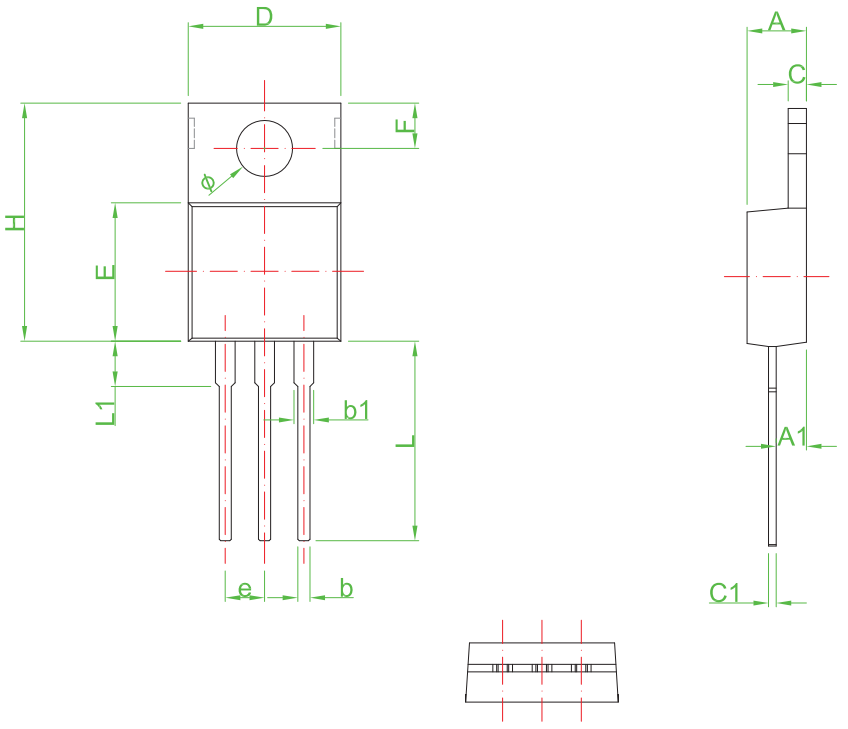
Fig.11 Unclamped Inductive Switching Waveform

Ordering and Marking Information

Ordering Device No.	Marking	Package	Packing	Quantity
ASDM60N170P-T	60N170	TO-220	Tube	50/Tube

PACKAGE	MARKING
TO-220	

TO-220 PACKAGE IN FORMATION



Symbol	Dimensions In Millmeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.00	4.80	0.157	0.189
A1	1.80	2.80	0.071	0.110
b	0.60	1.00	0.024	0.039
b1	1.14	1.78	0.045	0.070
C	1.00	1.40	0.039	0.055
C1	0.36	0.61	0.014	0.024
D	9.90	10.50	0.390	0.413
E	8.38	9.20	0.330	0.362
e	2.54 TYP		0.100 TYP	
F	2.54	3.20	0.100	0.126
ø	3.50	3.90	0.138	0.154
H	14.48	15.87	0.570	0.625
L	13.00	13.80	0.512	0.543
L1	---	4.10	---	0.161

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